

# Study of solar cells by using MOSFET implemented with the Diamond layout style

Rafael Rivas Valdivia  
Electric engineering department  
FEI university center  
São Paulo, Brazil  
uniervaldivia@fei.edu.br

Salvador Pinillos Gimenez  
Electric engineering department  
FEI university center  
São Paulo, Brazil  
sgimenez@fei.edu.br

**Abstract**—This work aims to perform an initial study of solar cell implemented by a planar structure based on the Metal-Oxide-Semiconductor Field Effect Transistor (MOSFET) biased and implemented with the Diamond (hexagonal gate shape) layout style. The experimental data have shown that the Diamond MOSFET can be considered as an alternative base cell to be used to implement solar cells.

**Keywords**—Solar cells, MOSFETs, Unconventional gate Layout Styles for MOSFETs.

## I. INTRODUCTION

The solar energy is one of the fastest growing renewable sources in the world and one of the most popular. In 2016 around 350 TWh were produced in the world and this energy could represent 30% of the electricity generated in the world in 2022, according to the International Energy Agency (IEA) [1].

One of the big problems with this technology is that its efficiency is very low, resulting in an increase in the cost its implementation [2]. The most used photovoltaic cells nowadays are made of crystalline silicon [3]. They occupy a large part of the international solar energy market [3]. The great advantage of the solar cell is that it has a relatively small production cost due to the great abundance of silicon in the world. Researchers from all over the world don't measure efforts to improve the electrical performance of this devices and therefore there are a lot of researches in this engineering area, such as studies for improve the methods of the electrical energy transmission and storage, and a large part of the researches in the generation area, such as the use of new surface texturing processes of the solar cells [4], anti-reflective coating engineering [5], among others. It is known that the innovative layout styles are capable of improve the electrical performance of the MOSFETs [6],[7]. In this scenario, the motivation of this paper is to perform an initial study of solar cell implemented by a planar structure based on the Metal-Oxide-Semiconductor Field Effect Transistor (MOSFET) biased and implemented with the Diamond (hexagonal gate shape) layout style focusing on improving its electrical performance [8]. This work proposes an innovative idea, there are no previous studies on this device as a solar cell.

## II. LITERATURE REVIEW

### A. Photoelectric effect

The photoelectric effect is based on the emission of energy packages called photons through electromagnetic radiations. The photons are particles that have an energy of their own. This energy ( $E$ ) can be calculated using Equation (1) [9].

$$E = h * v \quad (1),$$

where  $h$  is the Plank constant and  $v$  is the photon frequency. The photoelectric effect usually occurs on metal plates exposed to electromagnetic radiations. When the photons strike the metal surface, they can transfer their energies to the electrons, removing them from the metal with a certain kinetic energy (KE). This only occurs when the photon has energy superior to the working function of the material ( $\Phi$ ) [9].

### B. Typical solar cell

The solar cell is the device used to convert light energy into electrical energy through the photovoltaic effect. Today's solar cells are mostly made of crystalline silicon. These cells have an efficiency that can vary between 14% and 22%, but their production cost is relatively low. When grouped, they are called solar panel [10].

When these cells are exposed to electromagnetic radiations the photoelectric effect occurs, releasing the electrons from the material. They are captured in the form of electrical current, this is called photocurrent ( $I_{ph}$ ). On the other hand, when the solar cell is not exposed to electromagnetic radiations, it does not generate any type of electrical current or voltage and works as a diode and produce an electrical current called diode current ( $I_D$ ) [10]. The equivalent electrical circuit is illustrated in Figure 1 [11].

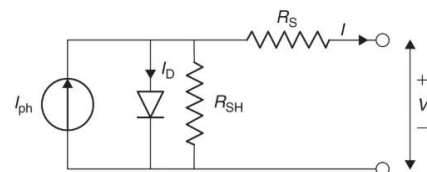


Figure 1: Electrical circuit equivalent of a solar cell [11].

In Figure 1,  $I_{ph}$  is photocurrent,  $I_D$  is the electrical current of the diode,  $R_S$  is the series electrical resistance, which corresponds to the solar cell's internal series resistance,  $R_{SH}$  is a shunt electrical resistance and  $V$  and  $I$  are respectively, the output electrical voltage and current, generated by the solar cell. The electric current generated of the solar cell ( $I$ ) can be obtained through the difference between  $I_{ph}$  and  $I_D$  to added the current that flows by the  $R_{SH}$  and  $V$  is calculated by the difference between the potential difference of the parallel connection, given by  $I_{ph}$ , the diode and  $R_{SH}$ , and the potential difference of  $R_S$ . Figure 2 shows the cross-section of a typical solar cell [11].

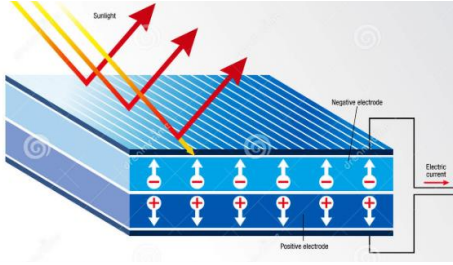


Figure 2: Cross-section of a typical solar cell [12].

### C. Metal-Oxide-Semiconductor Field Effect Transistor

The Metal-Oxide-Semiconductor Field Effect Transistor with insulated gate, covers many applications in the electronics environment. The conventional MOSFETs have a rectangular gate geometry. Figure 3 shows the cross-section of this kind of device [13]. This device presents four terminals: the drain, gate, source and body (substrate). There are two different types of MOSFETs: channel p (pMOSFET) and channel n (nMOSFET). Besides, these devices work in different operation modes: accumulation and enhancement. In this paper we are focusing on the enhancement mode. The two types of MOSFETs follow the same operation principle, but each one has a type of doping in the channel region (pMOSFET: n type substrate and nMOSFET: p type substrate) [13].

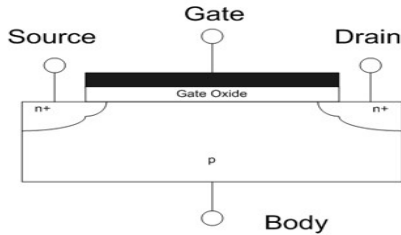


Figure 3: Example of a simplified cross-section of a conventional nMOSFET [14].

In Figure 3, n+ is the strongly doped region with pentavalent elements and p represents a weakly doped region with trivalent elements.

Between the gate and substrate regions there are a very thin layer of silicon dioxide ( $SiO_2$ ), which it is an excellent insulator. To form an electrode in the gate, a metal is placed on top of this oxide, forming the gate contact. A metal is also deposited on top of the source, drain and substrate regions, establishing a contact area on top of each one of them [13].

When an external voltage is applied between the gate and source ( $V_{GS}$ ), which must be bigger than the threshold voltage ( $V_{TN}$ ), a channel composed of mobile charge carriers is created between the source and drain regions, and consequently generating an electrical current flow in the longitudinal direction, since there is a potential difference between drain and source regions, i.e., from drain to source regions ( $I_D$ ), which is directly proportional to the ratio of the width ( $W$ ) by the length ( $L$ ) channel. Besides,  $I_D$  can be controlled by application of  $V_{GS}$  and  $V_{DS}$  [13]. There are three operating modes in this device: I- the cut-off mode, where there is no current flow ( $V_{GS}$  is small than  $V_{TN}$ ); II- the triode mode, where it has a similar operation to a resistor ( $V_{GS}$  higher or equal to  $V_{TN}$  and  $V_{DS}$  smaller than  $V_{GT} = V_{GS} - V_{TN}$ , which  $V_{GT}$  is called as 'overdrive gate voltage'); III- the saturation mode, which seems to behave as a current source ( $V_{GS}$  higher or equal to  $V_{TN}$  and  $V_{DS}$  higher or equal to  $V_{GT}$ ). Figure 4 illustrates  $I_D$  as a function of  $V_{DS}$  for four different values of  $V_{GS}$  ( $V_{GS1}$ ,  $V_{GS2}$ ,  $V_{GS3}$ ,  $V_{GS4}$ ). It shows the three operating modes of nMOSFET (cut-off, triode and saturation), which  $V_{DS(sat)}$  is the value of  $V_{DS}$  which the transistor operates between the triode and saturation regions [13].

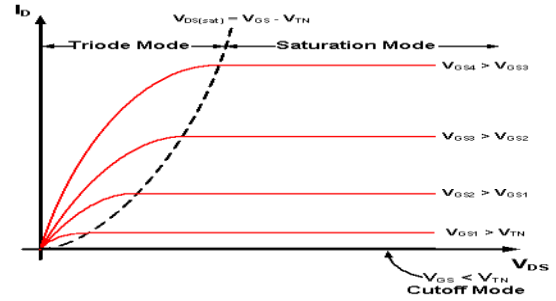


Figure 4: Characteristic curves  $I_D$  as a function of  $V_{DS}$  for different  $V_{GS}$  values [15].

Figure 5 presents the other characteristic curve of the nMOSFETs ( $I_D$  as a function of  $V_{GS}$ ) regarding a  $V_{DS}$  value. Note that, as the  $V_{GS}$  is smaller than  $V_{TN}$ ,  $I_D$  is practically null [13].

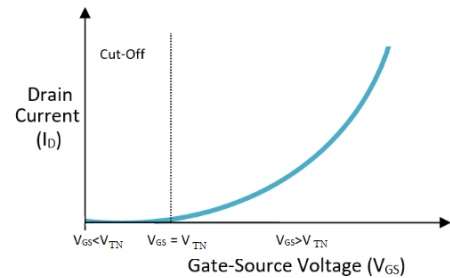


Figure 5: Characteristic curve  $I_D$  vs  $V_{GS}$  [16].

The simple mathematics model that describes nMOSFET  $I_D$  in the cut-off, triode and the saturation regions are given by Equation (2):  $I_D$ , Equation (3):  $I_D(\text{lin})$  and Equation (4):  $I_D(\text{sat})$ , respectively [13].

$$I_D = 0 \quad (2),$$

$$I_D(\text{lin}) = \frac{\mu_n \cdot C_{ox}}{2} \cdot \frac{W}{L} \cdot [2 \cdot (V_{GS} - V_{TN}) \cdot V_{DS} - V_{DS}^2] \quad (3),$$

$$I_D(\text{sat}) = \frac{\mu_n \cdot C_{ox}}{2} \cdot \frac{W}{L} \cdot (V_{GS} - V_{TN})^2 \cdot (1 + \lambda \cdot V_{DS}) \quad (4),$$

where  $\mu_n$  is the mobile charge carriers in the channel,  $C_{ox}$  is the oxide capacitance per area unit and  $\lambda$  is MOSFET parameter [13].

#### D. MOS-structure solar cell

The MOS-structure solar cell consists of an n-type layer on a p-type silicon (Substrate), a thin gate oxide ( $\text{SiO}_2$ ) layer, a transparent Indium Tin Oxide (ITO) gate electrode, two ohmic contacts on the drain and source regions, an electrode on the back (substrate) and an auxiliary voltage source, as shown in Figure 6 [17].

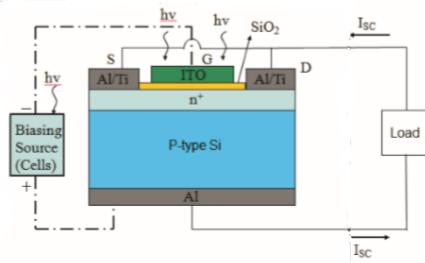


Figure 6: Example of a cross-section of a MOS-Si photovoltaic cell with the gate biased by an external voltage source and the source and drain terminals are short-circuited [17].

In Figure 6, the drain and source contacts are short-circuited and connected to a load, which in turn is connected to the substrate electrode. There is an external auxiliary voltage source connected to the gate of the MOS-structure through of its negative terminal, while its positive terminal is connected to the substrate contact. The external voltage source induces negative charges in the gate and therefore the majority carriers are repelled of the n+ region and consequently reducing the depletion region between n-type and p-type silicon placed in the substrate of the device. Therefore, this approach facilitates the flow of electrons of the n+ semiconductor to the p semiconductor and consequently increasing the value of  $I_{SC}$ , as this device is submitted the electromagnetic radiations (Figure 7). The electromagnetic radiations incidence in the device go through the gate, striking the n-type material and in some cases hitting the p-type material as well. When the photons strike in the n+ material, the electrons of the valence band can gain energy enough to pass to the conduction band, which are collected by the drain and source regions to compose the electric current ( $I_{SC}$ ) [17].

In Fig. 7,  $V_G$  is the potential energy of the gate in relation to the ground.

Regarding a  $V_G$  of 5V, Fig.7 shows that the  $I_{SC}$  is 12.93% higher than the one measured, as  $V_G$  is equal to 0V [17].

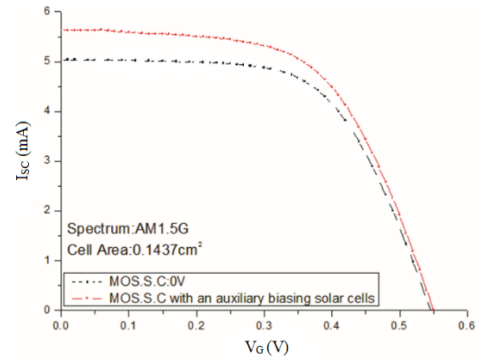


Figure 7: Photovoltaic  $I_{SC}$ - $V_G$  characteristics of an MOS-structure solar cell measured under AM1.5G illumination and biased with an auxiliary source ( $V_{oc} = 5$  V) [17].

#### E. Diamond MOSFET

The Diamond MOSFET (DM) is a transistor with a non-conventional gate geometry, that is, its gate geometry is not rectangular, that in this case it is hexagonal. Because of this change of the gate shape, this device presents the longitudinal corner effect which boost the longitudinal electric field along of channel [18]. This change enhances its electrical performance, increasing the drain current ( $I_{DS}$ ), the maximum effective mobility ( $\mu_{eff}$ ) and the transconductance ( $g_m$ ) and, in addition to reducing the on-state series resistance ( $R_{on}$ ), as compared to those of the conventional rectangular MOSFET. The disadvantage of this technology is to present its off-state drain current ( $I_{off}$ , at  $V_{GS}=0$ ) greater than the one of the conventional rectangular MOSFET, which increases the power consumed in the device and can limit its use in the digital applications. The structure of Diamond SOI MOSFET (DSM) is shown in Figure 8 [18].

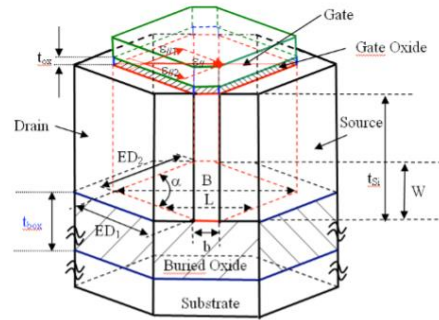


Figure 8: Diamond SOI MOSFET structure [18].

In Figure 8,  $t_{si}$ ,  $t_{ox}$  and  $t_{box}$  are the silicon film, the gate-oxide and buried-oxide thickness,  $B$  and  $b$  are the largest and smallest channel lengths, respectively, and  $\alpha$  is the angle between the sides  $ED_1$  and  $ED_2$  of the trapezoidal structure of the gate. Because of the new gate geometry of the Diamond MOSFET, three new effects are generated in its structure: The Longitudinal Corner Effect (LCE), the Parallel Connections of MOSFETs with Different Channel Lengths (PAMDLE) and the Deactivation of Parasitic MOSFTs in the Bird's Beak Regions (DEPAMBBRE) [18-19]. These effects boost the MOSFET

electrical performance in relation to the one found in the conventional MOSFET, regarding that they present the same gate area and bias conditions.

### III. EXPERIMENTAL RESULTS

In order to understand the advantages and disadvantages of a Diamond MOSFET in comparison to the conventional one counterpart (same gate area and bias conditions), electrical characterizations were performed. These devices were fabricated with 180 nm Bulk CMOS ICs manufacturing process of TSMC.

Regarding that the two devices were submitted to the same bias conditions. Figure 9 shows the curves of drain current ( $I_{DS}$ ) normalized by the aspect ratio [ $I_{DS}/(W/L)$ ] as a function of  $V_{DS}$  for  $V_{GS}$  equal to 0.5V of a DSM and its corresponding Conventional SOI MOSFET counterpart (CSM), regarding that they present the same  $V_{TNs}$  (0.29 V).

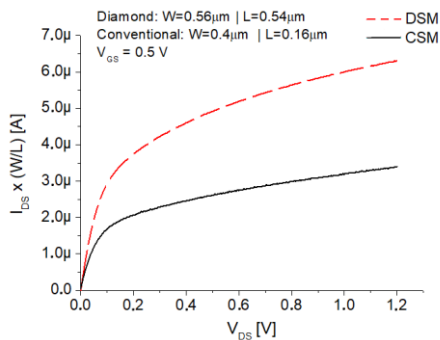


Figure 9:  $I_{DS}/(W/L)$  versus  $V_{DS}$  curves of CSM and DSM, for  $V_{GS}=0.5V$

Observing Figure 9, we can notice that the Diamond MOSFET  $I_{DS}/(W/L)$  is higher than the one found in the conventional counterpart in all operation modes, thanks to the LCE and PAMDLE effects [18]. Besides, regarding  $V_{DS}$  equal to 0.8V (saturation region),  $I_{DS}/(W/L)$  of the Diamond MOSFET is 53.79% higher than that measured in the conventional counterpart.

The continuation of this work is to implement a new structure for the solar cell considering a base cell defined by the Diamond MOSFET that will be biased by using an external voltage source. After that, three dimensional (3D) numerical simulations will be performed in order to verify the electrical performance of the solar cell implemented with Diamond MOSFETs in relation of that implemented with rectangular MOSFETs.

### IV. CONCLUSION

In order to boost the electrical performance of the solar cells, an innovative structure is been proposed for its implementation

which considers the use of Diamond MOSFETs biased. The next step of this work is to create this innovative structure of solar cell in the 3D numerical simulation and perform its electrical characterization. Besides, we will perform a comparative study of this new structure with the typical one, regarding the same areas.

### REFERENCES

- [1] Renewable electricity generation by source (non-combustible), World 1990-2017, [https://www.iea.org/data-and-statistics?country=WORLD&fuel=Energy%20supply&indicator=Renewable%20electricity%20generation%20by%20source%20\(non-combustible\)](https://www.iea.org/data-and-statistics?country=WORLD&fuel=Energy%20supply&indicator=Renewable%20electricity%20generation%20by%20source%20(non-combustible)), 2019.
- [2] Johnson Imhoff “ Desenvolvimento de conversores estáticos para sistemas fotovoltaicos autônomos”. Santa Maria, RS, Brazil. 2007.
- [3] Ruy F. “<https://blog.bluesol.com.br/energia-solar-fotovoltaica-guia-supremo/>”. Brasil, 2019.
- [4] H. Morikawa, D. Niinobe, K. Nishimura, S. Matsuno, S. Arimoto. “Processes for over 18.5% high-efficiency multi-crystalline silicon solar cell”, *Curr. Appl. Phys.* 10 (2010) S210-S214.
- [5] M.F. Schubert, F.W. Mont, S. Chhajed, D.J. Poxson, J.K. Kim, E.F. Schubert. “Design of multilayer antireflection coatings made from co-sputtered and low-refractive-index materials by genetic algorithm”, *Opt. Express* 16 (2008) 251108-1-251108-3
- [6] L. E. Seixas Jr, A. C. C. Telles, S. Finco, M. A. G. Silveira, N. H. Medina and S. P. Gimenez, “Study of Proton Radiation Effects Among MOSFETs Designed with Hexagonal and Rectangular Gate Geometries”, *IEEE Transactions on Nuclear Science*, 2016.
- [7] S. P. Gimenez, Daniel Manha, “Electrical Behavior of the Diamond layout for MOSFETs in X-rays ionizing radiation environments”, Elsevier 2015.
- [8] Vinicius Vono Peruzzi; Christian Renaux; Denis Flandre, Salvador Pinillos Gimenez “Boosting the MOSFETs Matching by Using Diamond Layout Style”, *IEEE Journal of Integrated Circuits and Systems* 2017.
- [9] Jonas Rafael Gazoli “Energia Solar Fotovoltaica conceitos e aplicações”, Érica, 2018.
- [10] Jacob Fraden. “Handbook Of Modern Sensors Physics Design And Applications 3<sup>o</sup> edition”, California 2003.
- [11] Soteris Kalogirou. “Engenharia-de-Energia-Solar”, Elsevier Inc.2014.
- [12] Alejomiranda, <https://www.istockphoto.com/br/vetor/se%C3%A7%C3%A3o-transversal-de-uma-c%C3%A9lula-solar-energias-renov%C3%A1veis-gm913315880-251411222>, 2018.
- [13] Adel S. Sedra , Kenneth C. Smith “microeletrônica 5 edição”, Pearson 2007.
- [14] Nobuo Oki, “Física Básica do Dispositivo MOS”, Brasil 2013.
- [15] [http://www.cmm.gov.mo/eng/exhibition/secondfloor/MoreInfo/2\\_10\\_4\\_HowFETWorks.html](http://www.cmm.gov.mo/eng/exhibition/secondfloor/MoreInfo/2_10_4_HowFETWorks.html), Museu das comunicações, data da última modificação 11/06/2019.
- [16] Sourav Gupta, <https://circuitdigest.com/tutorial/what-is-mosfet-basics-types-working-and-amplifier-design>, 2019.
- [17] Q.R. Lai \*, W.J. Ho\*, J.J. Liu\*, Y.Y. Lee\*, C.C. Liao\*, J.Y. Wu\*, and Y.C. Chiu\* “Photocurrent of MOS-Si Photovoltaic Device Enhanced by an Auxiliary Biasing Solar Cell” Busan, Korea, 2012.
- [18] Salvador Pinillos Gimenez, “Diamond MOSFET: A Novel and Simple Structure Implemented by Drain/Channel/Source Interfaces Engineering Approach for Analog and Digital Integrated Circuits Applications”, *Solid-State Electronics*, 2010.
- [19] Salvador Pinillos Gimenez, *Layout Techniques for MOSFETs*, Publisher: Morgan & Claypool, 2016.